

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings, of claims in the application:

LISTING OF CLAIMS:

1. - 9. (Canceled)

10. (Currently Amended) The adhesive resin according to Claim [[8]] 15,
further comprising a thermosetting resin except which is not a polyimide resin.

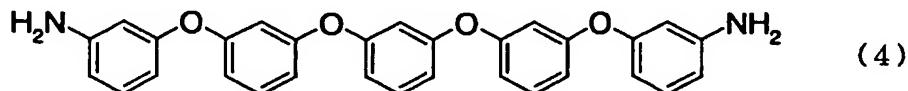
11. (Currently Amended) The adhesive resin according to Claim [[8]] 10,
wherein the thermosetting resin comprises an epoxy resin, and the adhesive resin
further comprises an epoxy resin-curing agent.

12. (Currently Amended) The adhesive resin according to Claim [[8]] 15,
comprising inorganic filler.

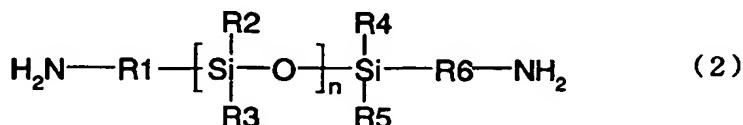
13. (Currently Amended) A film adhesive comprising the adhesive resin
according to Claim [[8]] 15.

14. (Currently Amended) A semiconductor device wherein a semiconductor
element is attached to a support by the film adhesive according to Claim [[6]] 15.

15. (New) An adhesive resin comprising a polyimide resin obtained by reacting a diamine component containing a diamine represented by the following formula (4) as an essential component with a tetracarboxylic dianhydride component,

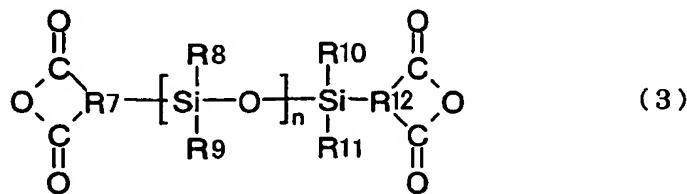


wherein the diamine component further comprises a diamine represented by the following formula (2) as a diamine component,



(wherein R1 and R6 are divalent aliphatic groups having 1 to 4 carbon atoms or aromatic groups; R2 to R5 are monovalent aliphatic groups or aromatic groups; and n is an integer of 0 to 20)

and/or the tetracarboxylic dianhydride component further comprises a tetracarboxylic dianhydride represented by the following formula (3) as the tetracarboxylic dianhydride component,



(wherein R7 and R12 are trivalent aliphatic groups or aromatic groups; R8 to R11 are monovalent aliphatic groups or aromatic groups; the carbon skeleton of the acid anhydride structure is a 5- or 6-membered ring; and n is an integer of 0 to 20).